## MICROWAVE POWER GaAs FET

## Internally Matched Power GaAs FETs (X, Ku-Band)

#### **Features**

- · High power
  - $P_{1dB}$  = 39.5 dBm at 8.5 GHz to 9.6 GHz
- · High gain
- G<sub>1dB</sub> = 6.0 dB at 8.5 GHz to 9.6 GHz
   Broadband internally matched
- · Hermetically sealed package

### RF Performance Specifications ( $T_a = 25^{\circ}C$ )

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Output Power at 1dB Compression Point	P <sub>1dB</sub>	V <sub>DS</sub> = 9V - f = 8.5 - 9.6 GHz	dBm	38.5	39.5	-
Power Gain at 1dB Compression Point	G <sub>1dB</sub>		dB	5.0	6.0	-
Drain Current	$I_{DS}$		Α	-	3.4	4.4
Power Added Efficiency	η <sub>add</sub>		%	-	22	-
Channel-Temperature Rise	$\Delta T_{ch}$	V <sub>DS</sub> x I <sub>DS</sub> x R <sub>th (c-c)</sub>	°C	-	-	80

### Electrical Characteristics (T<sub>a</sub> = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	$V_{DS} = 3V$ $I_{DS} = 4.0A$	mS	-	2400	-
Pinch-off Voltage	V <sub>GSoff</sub>	$V_{DS} = 3V$ $I_{DS} = 120 \text{ mA}$	V	-2	-3.5	-5
Saturated Drain Current	I <sub>DSS</sub>	$V_{DS} = 3V$ $V_{GS} = 0V$	Α	-	8.0	10.4
Gate-Source Breakdown Voltage	$V_{GSO}$	I <sub>GS</sub> = -120 μA	V	-5	-	-
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to Case	°C/W	-	1.6	2.5

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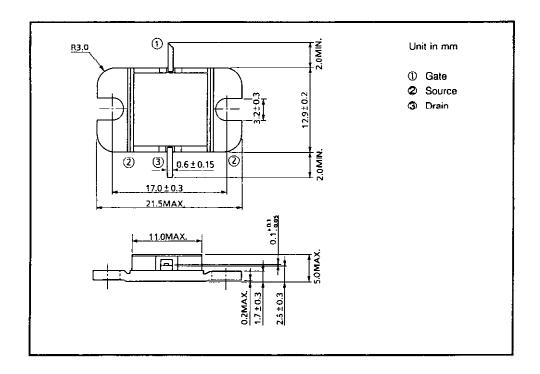
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# Absolute Maximum Ratings ( $T_a = 25^{\circ}C$ )

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	$V_{DS}$	V	15
Gate-Source Voltage	$V_{GS}$	V	-5
Drain Current	I <sub>D</sub>	Α	10.4
Total Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>T</sub>	W	60
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	.C	-65 ~ 175

### Package Outline (2-11C1B)

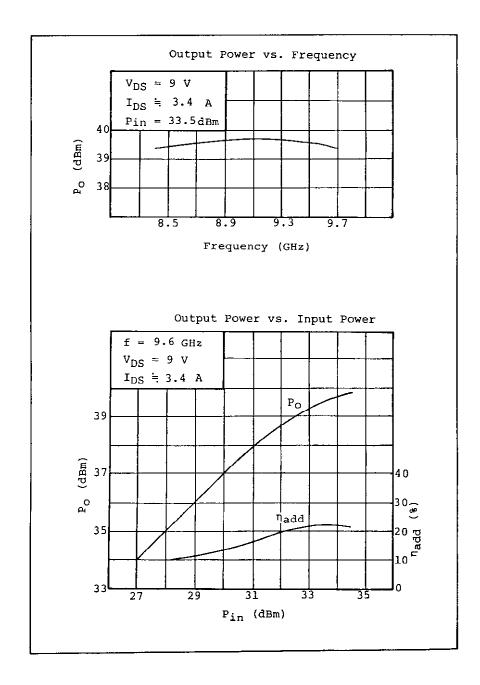


## **Handling Precautions for Packaged Type**

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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### **RF Performances**



## **Power Dissipation vs. Case Temperature**

